

Amendments to the Specification

IN THE TITLE

Please change USPTO records to indicate that the title to be used in this application is ---ELECTROLESS COPPER PLATING SOLUTION AND ELECTROLESS COPPER PLATING METHOD---, which title coincides with the title appearing in the English translation of the specification.

IN THE WRITTEN DESCRIPTION

Please replace paragraph [0008] with the following amended paragraph:

[0008]

Specifically, the present invention is as follows.

(1) An electroless copper plating ~~solution~~method, wherein, ~~along with a first reducing agent,~~using an electroless copper plating solution comprising hypophosphorous acid or a hypophosphite is used as a second reducing agent, ~~and a stabilizer to inhibit copper deposition is further used at the same time along with a first reducing agent and further comprising a stabilizer to inhibit copper deposition at the same time,~~a mirror surface whose average surface roughness is less than 10 nm is electroless plated to produce a thin film with a thickness of 500 nm or less.

(2) An electroless copper plating ~~solution~~method according to (1) above, ~~which is used to produce a thin film with a thickness of 500 nm or less wherein a pretreatment agent is prepared by reacting or mixing in advance a noble metal compound and a silane coupling agent having a functional group with metal capturing capability, and said mirror surface is treated with the pretreatment agent.~~

(3) An electroless copper plating method, ~~wherein an electroless copper plating solution according to (1) or (2) above is used to perform electroless copper plating on a mirror surface whose average surface roughness is less than 10 nm,~~wherein the first reducing agent is glyoxylic acid, the second reducing agent is hypophosphorous acid and the stabilizer to inhibit copper deposition is 2,2'-bipyridyl.